

Company		DUNS#	URL For Additional Information
National Semiconductor		04-147-2986	http://www.national.com/analog/quality/green

Contact	Title	Phone	Email
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Part Number	MSL Rating	Peak Body Temp C	MaxTime(Sec)	Cycles	Unit Type
ADC0831CCWM	3	260	40	4	Each

Document Date	European RoHS Compliant. China RoHS Compliant.	Weight (mg)	Does NOT Contain Halogens
05-20-2009		359.28	

Homogeneous Material Composition Declaration for Electronic Products

Item	Weight (mg)	Component	CAS#	Weight (mg)	Item-ppm	Part-ppm
Plastic	265.68	SiO2	60676-86-0	236.455	890,000	658,138
		Epoxy Resin	25928-94-3	21.254	80,000	59,157
		Mg(OH)2	1309-42-8	7.970	30,000	22,183
Leadframe	81.63	Cu	7440-50-8	79.548	974,500	221,410
		Fe	7439-89-6	1.959	24,000	5,453
		Zn	7440-66-6	0.098	1,200	273
		P	7723-14-0	0.024	300	67
Chip	5.80	Si	7440-21-3	5.765	994,000	16,046
		Al	7429-90-5	0.035	6,000	97
Ext. LeadFinish	4.80	Sn	7440-31-5	4.800	1,000,000	13,360
Die Attach	0.61	Ag	7440-22-4	0.458	750,000	1,275
		Epoxy Resin	25928-94-3	0.153	250,000	426
Int. LeadFinish	0.50	Ag	7440-22-4	0.500	1,000,000	1,392
Wires	0.26	Au	7440-57-5	0.260	1,000,000	724

Note: The device content disclosed herewith is approximate and is based on engineering estimates only. It has not been verified through analytical. Additionally, the following should be noted:

- One or more dopant materials may be present in the silicon die at sub-ppm levels to provide semiconductor properties.
- Epoxy resin components listed are generic and may or may not be the specific compound used, which is considered proprietary.

RoHS Material Composition Declaration

RoHS Directive 2002/95/EC	RoHS Definition: Quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury, Hexavalent Chromium, Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE) and quantity limit of 0.01% by mass (100 PPM) of homogeneous material for Cadmium
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Subject to the limitations below, National Semiconductor Corporation ("National") certifies the following information as of the document date.

- National products designated "ROHS Compliant" comply with the European Unions Directive on the Restriction of the Use of Hazardous Substances 2002/95/EC ("RoHS"). Certain National products contain lead in RoHS exempt applications 5, 7a or 7c.
- National products do not contain and are not manufactured with ozone depleting compounds.
- National products do not contain substances identified by the European Chemical Agency ("ECHA") as substances of very high concern ("SVHC").
- National products are manufactured in conformance with National specifications (SC)CSP-9-111C1 Supplier Environmental Requirements for Materials and Products and (SC)CSP-9-111S2 Banned and Reportable Substances.
- National's list of banned and reportable substances and management system is based on the current version of the Joint Industrial Guide, JIG-101.

National has taken commercially reasonable steps to provide representative and accurate information but may not have independently verified information provided or conducted chemical analysis of incoming materials. Equivalent compliant materials may have been substituted for those stated herein. Material concentrations are the maximum expected concentration of the substance in the device and may not represent the actual concentration. National and its suppliers consider certain limited information to be confidential and thus CAS numbers and other limited information may not be available for release. Nationals Standard Terms and Conditions of Sale apply to any issue arising out of or in connection with the information provided herein unless otherwise provided by a written contract signed by both parties.

NATIONAL ACCEPTS NO DUTY TO NOTIFY USERS OF THIS DECLARATION OF UPDATES OR CHANGES TO THIS DECLARATION.

 Gerry Edwards
Vice President Quality

Banned Substance Monitoring

Part Number	Document Date
ADC0831CCWM NOPB	05-20-2009

European RoHS Compliant.

China RoHS Compliant.

Item#	Material	Cd	CrVI	Pb	Hg	PBB	PBDE	Cl	Br	Ref#
1	CHIP	<1	<1	<1	<30	<10	<10	NA	NA	1000
2	COMPOUND	< 2	< 2	< 2	< 2	< 5	< 5	< 50	< 50	637
3	EPOXY	<2	<5	<5	<1	<10	<10	NA	NA	32
4	EXTLF	< 2	< 2	23	< 2	NA	NA	NA	NA	595
5	FRAME	< 2	< 2	11	< 2	NA	NA	NA	NA	52
6	WIRE	< 2	< 2	< 2	< 2	NA	NA	NA	NA	75

* Cd: Cadmium, CrVI: Hexavalent Chromium, Pb: Lead, Hg: Mercury, NA: Not Applicable

* Unless otherwise noted, units are in PPM (parts-per-million)

Ref#	3rd Party Analysis (available upon request, subject to a non-disclosure agreement)
1000	Analysis on 03/01/2009 by BALAZ as per Report# E008516J #01/LMP7300D6/VIP050L23
637	Analysis on 03/01/2009 by SGS per Report# 04522/09
32	Analysis on 03/01/2009 by SGS per Report# ATJB/1331BS/2009
595	Analysis on 03/01/2009 by SGS per Report# 04501/09
52	Analysis on 03/01/2009 by SGS per Report# 04536/09
75	Analysis on 03/01/2009 by SGS per Report# 04531/09